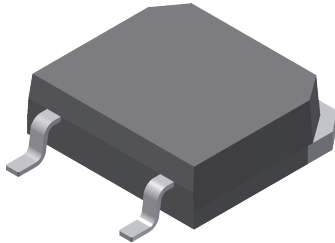


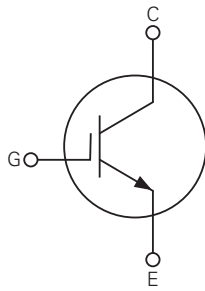
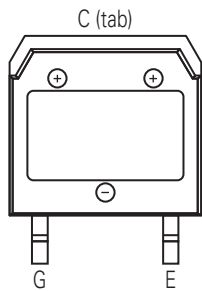
IXYT90N65A5HV

650 V, 90 A Gen5 XPT™ IGBT

Extreme Light Punch Through IGBT for up to 5 kHz Switching



Pinout Diagram (TO-268HV)



G: Gate; **C:** Collector; **E:** Emitter; **Tab:** Collector

Description:

Developed using our proprietary XPT™ thin-wafer technology and state-of-the-art Trench IGBT process, these devices feature reduced thermal resistance, low conduction losses, and low gate drive requirements.

Features & Benefits:

- Optimized for Low Conduction Losses
- High Surge Current Capability
- Square RBSOA
- International Standard Package
- Low Gate Charge Q_G
- Low Gate Drive Requirement

Applications:

- Power Inverters
- UPS
- PFC Circuits
- Battery Chargers
- Welding Machines
- Lamp Ballasts
- Inrush Current Protection Circuits

Product Summary

Characteristic	Value	Unit
V_{CES}	650	V
I_{C110}	90	A
$V_{CE(sat)}$	1.35	V
$t_{fi(typ)}$	270	ns

Maximum Ratings

Symbol	Characteristic	Conditions	Value	Unit
V_{CES}	Collector-Emitter Voltage	$T_J = 25\text{ °C to }175\text{ °C}$	650	V
V_{CGR}	Collector-Gate Voltage	$T_J = 25\text{ °C to }175\text{ °C}, R_{GE} = 1\text{ M}\Omega$	650	V
V_{GES}	Gate-Emitter Voltage	Continuous	± 20	V
V_{GEM}	Transient Gate-Emitter Voltage	Transient	± 30	V
I_{C25}	Continuous Collector Current	$T_C = 25\text{ °C}$ (Chip Capability)	220	A
I_{LRMS}	Terminal Current Limit	–	160	A
I_{C110}	Continuous Collector Current	$T_C = 110\text{ °C}$	90	A
I_{CM}	Pulsed Collector Current	$T_C = 25\text{ °C}, 1\text{ ms}$	600	A
SSOA (RBSOA)	Switching Safe Operating Area (Reverse Biased Safe Operating Area)	$V_{GE} = 15\text{ V}, T_{VJ} = 150\text{ °C}, R_G = 5\text{ }\Omega$, Clamped Inductive Load, $I_{CM} @ V_{CE} \leq V_{CES}$	180	A
P_C	Collector Power Dissipation	$T_C = 25\text{ °C}$	650	W
T_J	Junction Temperature	–	–55 to 175	°C
T_{JM}	Maximum Junction Temperature	–	175	°C
T_{stg}	Storage Temperature	–	–55 to 175	°C
T_{SOLD}	Soldering Temperature	Plastic Body for 10 s	260	°C
W	Weight	–	4	g

Thermal Characteristic

Symbol	Characteristic	Value			Unit
		Min.	Typ.	Max.	
$R_{th, JC}$	Thermal Resistance, Junction-to-Case	–	–	0.23	°C/W

Electrical Characteristics – Static ($T_J = 25\text{ °C}$ unless otherwise specified)

Symbol	Characteristic	Conditions	Value			Unit
			Min.	Typ.	Max.	
BV_{CES}	Collector-Emitter Breakdown Voltage	$I_C = 250\text{ }\mu\text{A}, V_{GE} = 0\text{ V}$	650	–	–	V
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C = 250\text{ }\mu\text{A}, V_{CE} = V_{GE}$	3.7	–	5.8	V
I_{GES}	Gate-Emitter Leakage Current	$V_{CE} = 0\text{ V}, V_{GE} = \pm 20\text{ V}$	–	–	± 100	nA
I_{CES}	Zero Gate Voltage Collector Current	$V_{CE} = V_{CES}, V_{GE} = 0\text{ V}$	–	–	5	μA
		$V_{CE} = V_{CES}, V_{GE} = 0\text{ V}, T_J = 150\text{ °C}$	–	–	500	μA
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage ¹	$I_C = 60\text{ A}, V_{GE} = 15\text{ V}$	–	1.22	1.35	V
		$I_C = 60\text{ A}, V_{GE} = 15\text{ V}, T_J = 150\text{ °C}$	–	1.30	–	V

Note 1: Pulse test, $t \leq 300\text{ }\mu\text{s}$, duty cycle, $d \leq 2\%$

Electrical Characteristics – Dynamic ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Symbol	Characteristic	Conditions		Value			Unit	
				Min.	Typ.	Max.		
g_{fs}	Transconductance ¹	$I_C = 60\text{ A}, V_{CE} = 10\text{ V}$		40	68	–	S	
C_{ies}	Input Capacitance	$V_{GE} = 25\text{ V}, V_{CE} = 0\text{ V}, f = 1\text{ MHz}$		–	4040	–	pF	
C_{oes}	Output Capacitance			–	200	–		
C_{res}	Reverse Transfer Capacitance			–	150	–		
$Q_{g(on)}$	Total Gate Charge	$V_{GE} = 15\text{ V}, V_{CE} = 0.5 \times V_{CES},$ $I_C = 90\text{ A}$		–	260	–	nC	
Q_{ge}	Gate-Emitter Charge			–	33	–		
Q_{gc}	Gate-Collector Charge			–	128	–		
$t_{d(on)}$	Turn-on Delay Time ²	Inductive Load, $V_{GE} = 15\text{ V}, V_{CE} = 400\text{ V},$ $I_C = 40\text{ A}, R_{G(ext)} = 5\text{ }\Omega$	$T_J = 25\text{ }^{\circ}\text{C}$	–	37	–	ns	
			$T_J = 150\text{ }^{\circ}\text{C}$	–	20	–		
t_{ri}	Turn-on Rise Time ²		$T_J = 25\text{ }^{\circ}\text{C}$	–	43	–	ns	
			$T_J = 150\text{ }^{\circ}\text{C}$	–	40	–		
E_{on}	Turn-on Energy ²		$T_J = 25\text{ }^{\circ}\text{C}$	–	1.0	–	mJ	
			$T_J = 150\text{ }^{\circ}\text{C}$	–	2.2	–		
$t_{d(off)}$	Turn-off Delay Time ²		$T_J = 25\text{ }^{\circ}\text{C}$	–	436	–	ns	
			$T_J = 150\text{ }^{\circ}\text{C}$	–	407	–		
t_{fi}	Turn-off Fall Time ²		$T_J = 25\text{ }^{\circ}\text{C}$	–	270	–	ns	
			$T_J = 150\text{ }^{\circ}\text{C}$	–	405	–		
E_{off}	Turn-off Energy ²		$T_J = 25\text{ }^{\circ}\text{C}$	–	3.0	–	mJ	
			$T_J = 150\text{ }^{\circ}\text{C}$	–	4.2	–		

Note 1: Pulse test, $t \leq 300\text{ }\mu\text{s}$, duty cycle, $d \leq 2\%$ **Note 2:** Switching times and energy losses may increase for higher $V_{CE(clamp)}$, T_J , or R_G .

Characteristic Curves

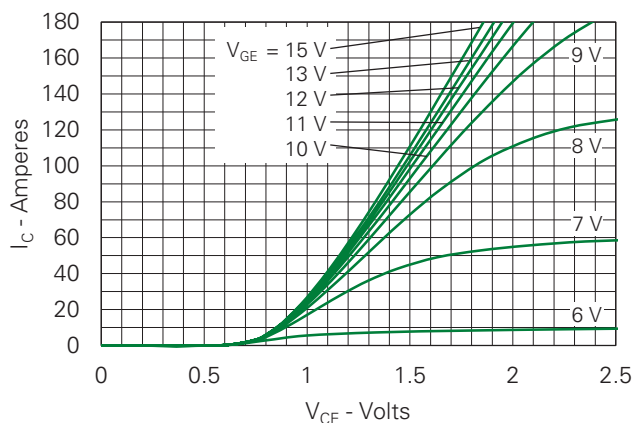
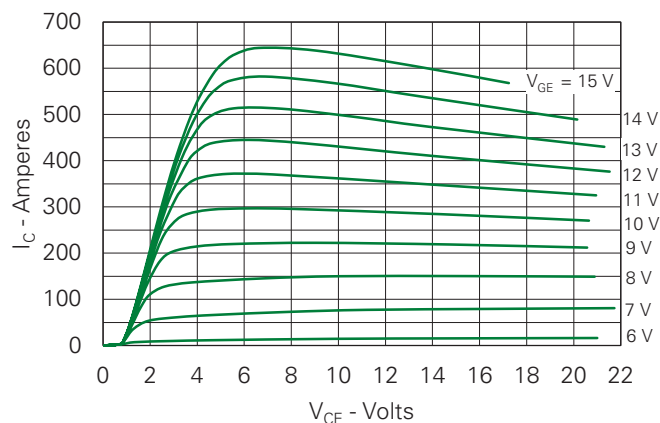
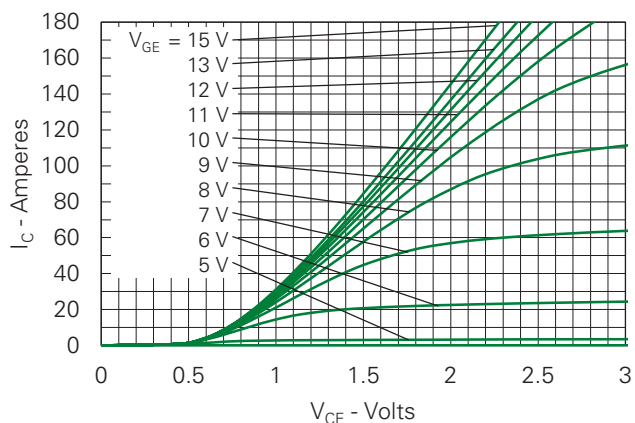
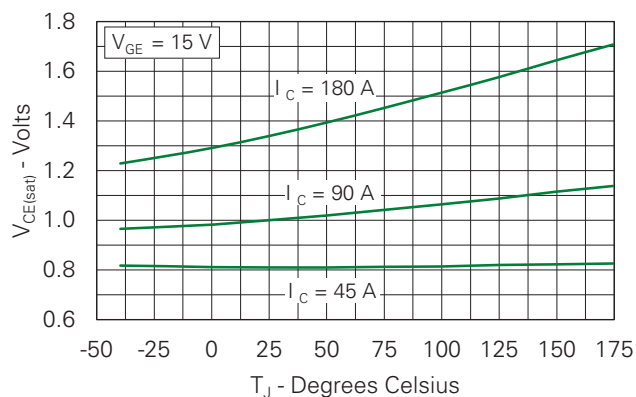
Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$ Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$ Fig. 3. Output Characteristics @ $T_J = 150^\circ\text{C}$ Fig. 4. Dependence of $V_{CE(sat)}$ on Junction Temperature

Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

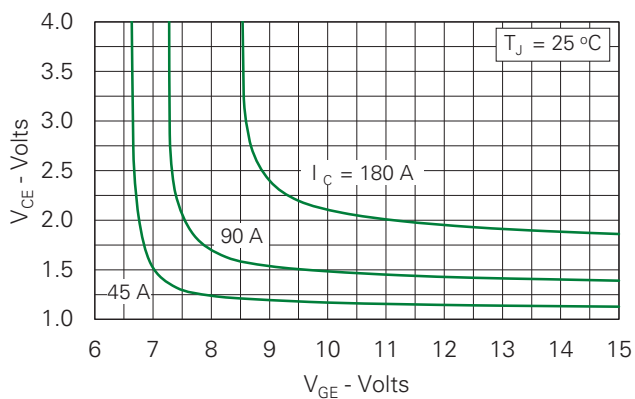


Fig. 6. Input Admittance

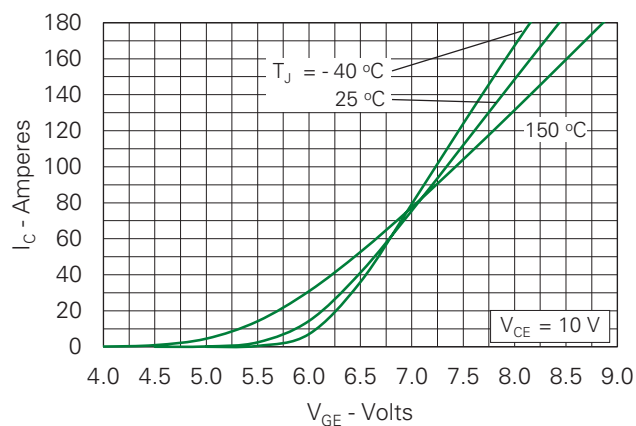


Fig. 7. Transconductance

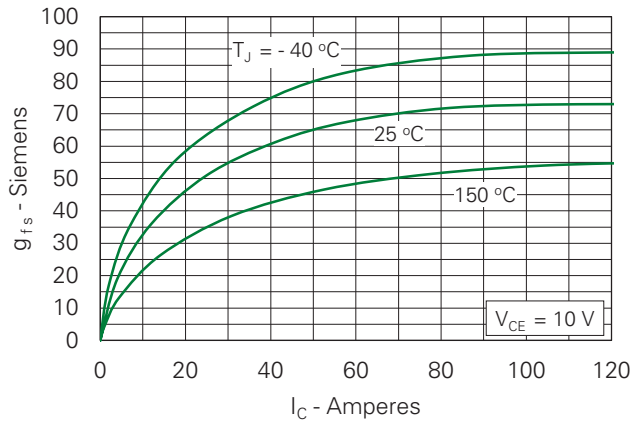


Fig. 8. Gate Charge

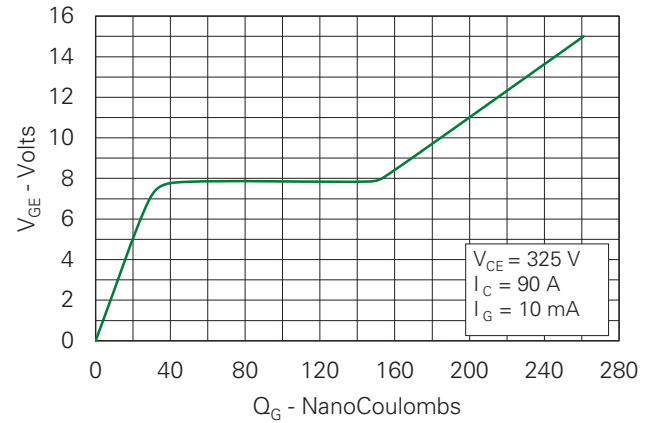


Fig. 9. Capacitance

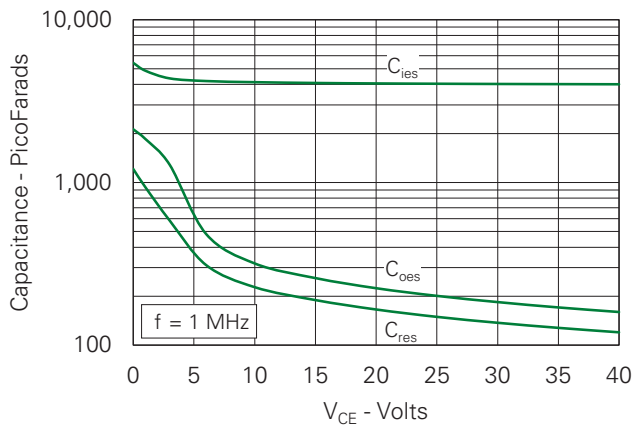


Fig. 10. Reverse-Bias Safe Operating Area

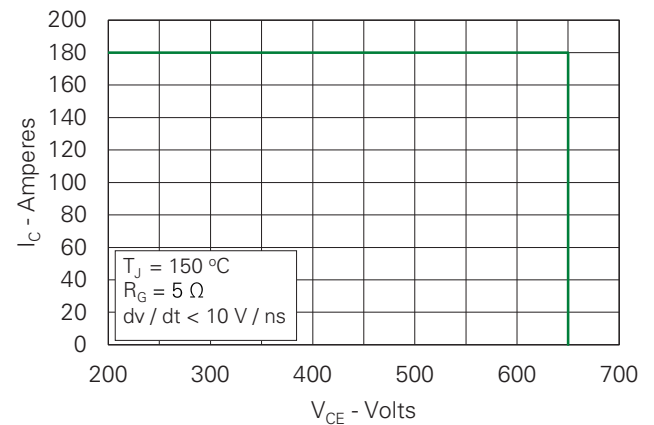


Fig. 11. Maximum Transient Thermal Impedance

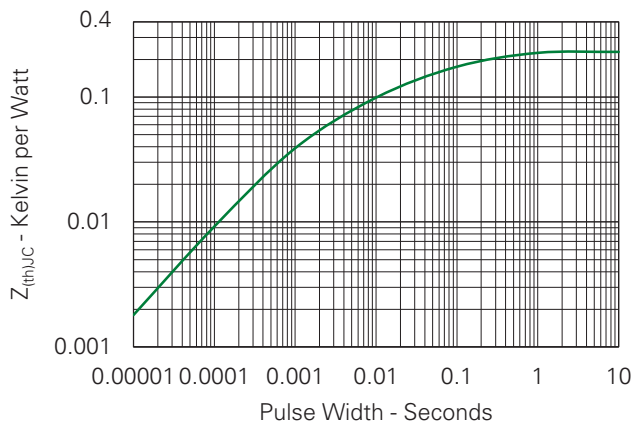


Fig. 12. Inductive Switching Energy Loss vs. Collector Current

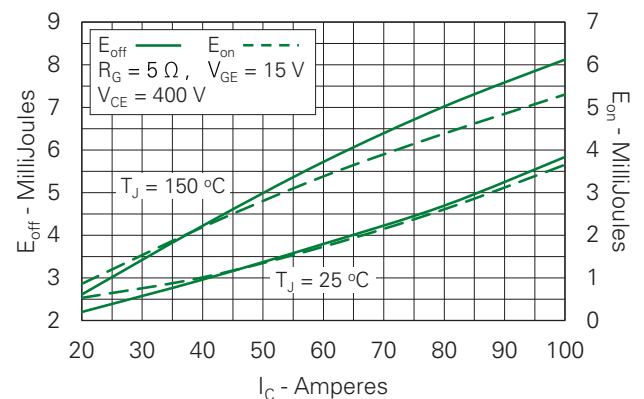


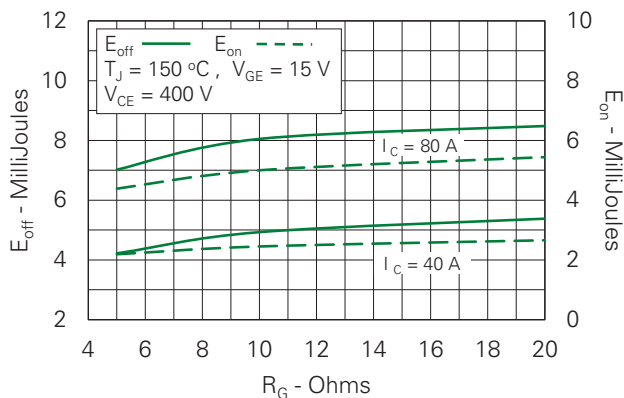
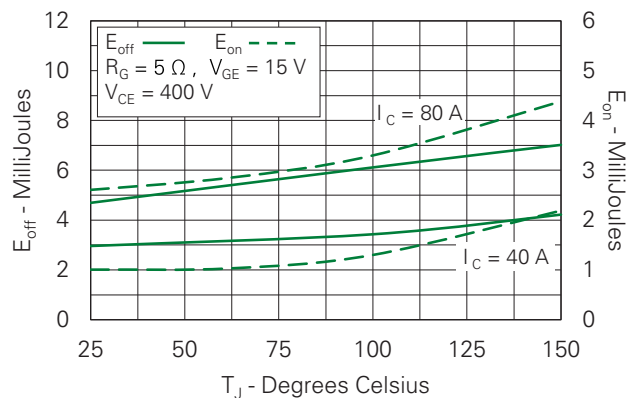
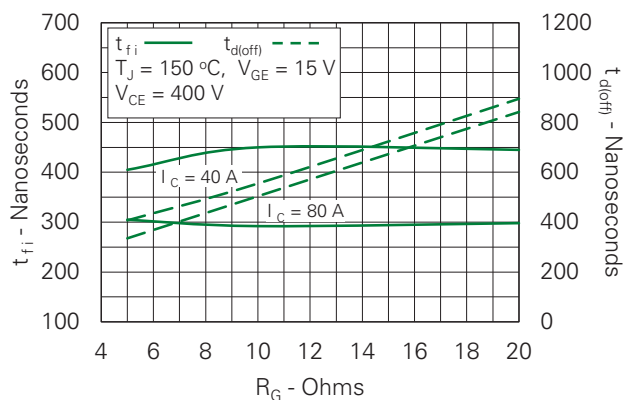
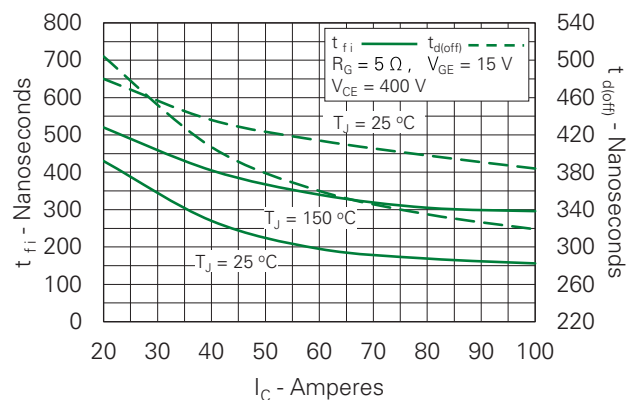
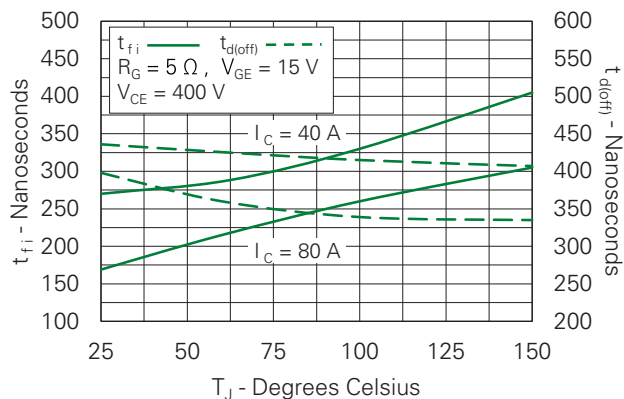
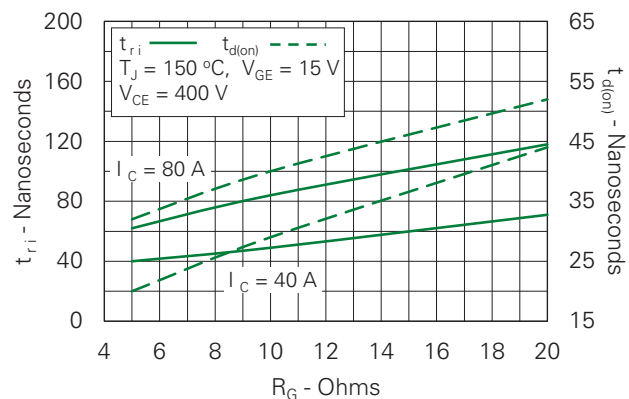
Fig. 13. Inductive Switching Energy Loss vs. Gate Resistance**Fig. 14. Inductive Switching Energy Loss vs. Junction Temperature****Fig. 15. Inductive Turn-off Switching Times vs. Gate Resistance****Fig. 16. Inductive Turn-off Switching Times vs. Collector Current****Fig. 17. Inductive Turn-off Switching Times vs. Junction Temperature****Fig. 18. Inductive Turn-on Switching Times vs. Gate Resistance**

Fig. 19. Inductive Turn-on Switching Times vs. Collector Current

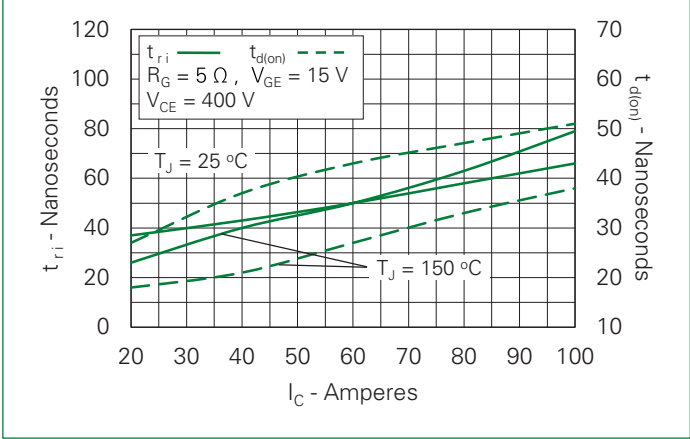


Fig. 20. Inductive Turn-on Switching Times vs. Junction Temperature

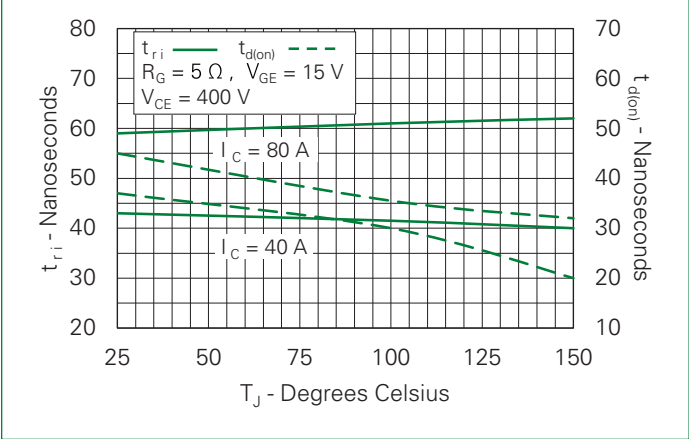
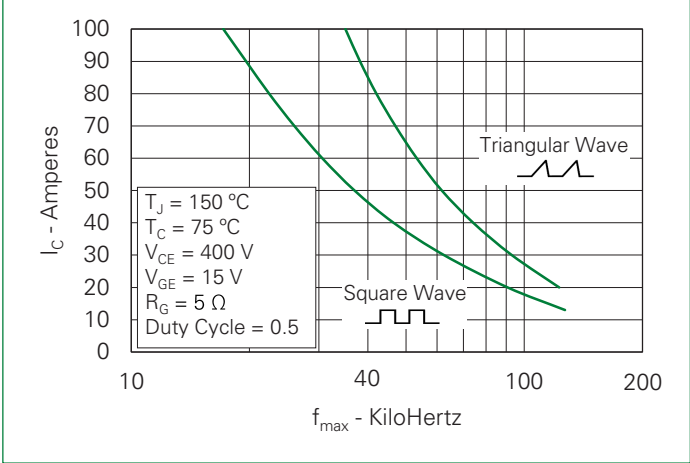
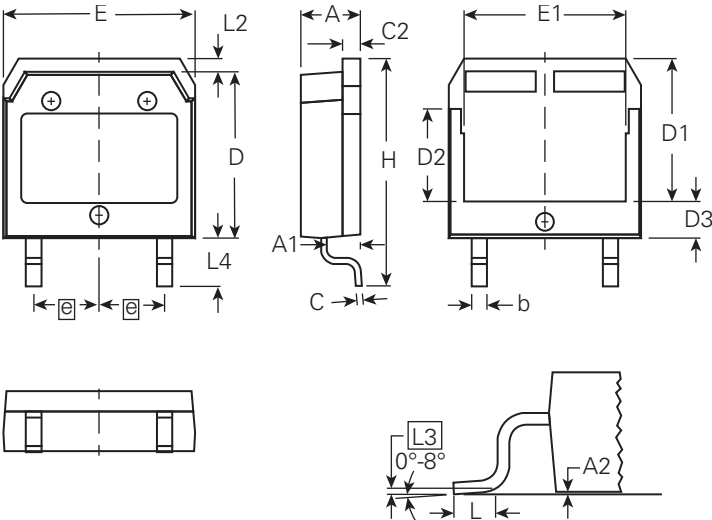


Fig. 21. Maximum Peak Load Current vs. Frequency



Part Outline Drawing (TO-268HV)



Symbol	Inches			Millimeters		
	Min.	Typical	Max.	Min.	Typical	Max
A	0.193	–	0.201	4.90	–	5.10
A1	0.106	–	0.114	2.70	–	2.90
A2	0.001	–	0.010	0.02	–	0.25
b	0.045	–	0.057	1.15	–	1.45
C	0.016	–	0.026	0.40	–	0.65
C2	0.057	–	0.063	1.45	–	1.60
D	0.543	–	0.551	13.80	–	14.00
D1	0.465	–	0.476	11.80	–	12.10
D2	0.295	–	0.307	7.50	–	7.80
D3	0.114	–	0.126	2.90	–	3.20
E	0.624	–	0.632	15.85	–	16.05
E1	0.524	–	0.535	13.30	–	13.60
e	0.215 BSC			5.45 BSC		
e2	0.374	–	0.386	9.50	–	9.80
H	0.736	–	0.752	18.70	–	19.10
L	0.067	–	0.079	1.70	–	2.00
L2	0.039	–	0.045	1.00	–	1.15
L3	0.010 BSC			0.25 BSC		
L4	0.150	–	0.161	3.80	–	4.10

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